

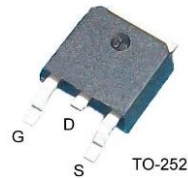
Features

- 650V, 5A
- $R_{DS(ON)} = 2.7\Omega$ (Max.) @ $V_{GS} = 10V, I_D = 2A$
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- RoHS and Halogen-Free Compliant

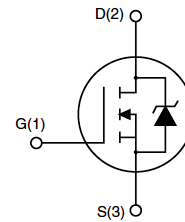
Application

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

Package



WFD5N65LFS



Absolute Maximum Ratings $T_C=25^\circ C$ unless otherwise specified

| Symbol | Parameter | Max. | Units |
|-----------------|--|--------------------------|--------------|
| V_{DSS} | Drain-Source Voltage | 650 | V |
| V_{GSS} | Gate-Source Voltage | ± 30 | V |
| I_D | Continuous Drain Current <small>note5</small> | $T_C = 25^\circ C$ 4 | A |
| I_{DM} | Pulsed Drain Current <small>note3</small> | 16 | A |
| P_D | Power Dissipation <small>note2</small> | $T_C = 25^\circ C$ 25 | W |
| E_{AS} | Single Pulse Avalanche Energy <small>note3,6</small> | 76 | mJ |
| $R_{\theta JC}$ | Thermal Resistance, Junction to Case | 5 | $^\circ C/W$ |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient <small>note1,4</small> | 60 | $^\circ C/W$ |
| T_J, T_{STG} | Operating and Storage Temperature Range | -55 to +150 | $^\circ C$ |

Electrical Characteristics $T_C=25^\circ\text{C}$ unless otherwise specified

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Units |
|----------------------------------|--|--|------|------|-----------|----------|
| Off Characteristic | | | | | | |
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0V, I_D = 250\mu A$ | 650 | - | - | V |
| I_{DSS} | Drain-Source Leakage Current | $V_{DS} = 650V, V_{GS} = 0V$ | - | - | 1 | μA |
| I_{GSS} | Gate to Body Leakage Current | $V_{DS} = 0V, V_{GS} = \pm 30V$ | - | - | ± 100 | nA |
| On Characteristics | | | | | | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_D = 250\mu A$ | 3 | - | 4 | V |
| $R_{DS(on)}$ | Static Drain-Source On-Resistance | $V_{GS} = 10V, I_D = 2A$ | - | 2.3 | 2.7 | Ω |
| Dynamic Characteristics | | | | | | |
| C_{iss} | Input Capacitance | $V_{DS} = 25V, V_{GS} = 0V,$ $f = 1.0MHz$ | - | 545 | - | pF |
| C_{oss} | Output Capacitance | | - | 53 | - | pF |
| C_{rss} | Reverse Transfer Capacitance | | - | 4.5 | - | pF |
| Switching Characteristics | | | | | | |
| Q_g | Total Gate Charge | $V_{DS} = 520V, I_D = 4A,$ $V_{GS} = 10V$ | - | 15 | - | nC |
| Q_{gs} | Gate-Source Charge | | - | 3 | - | |
| Q_{gd} | Gate-Drain("Miller") Charge | | - | 7 | - | |
| $t_{d(on)}$ | Turn-On Delay Time | $V_{DS} = 250V, I_D = 4A,$ $R_G = 25\Omega$ | - | 36 | - | ns |
| t_r | Turn-On Rise Time | | - | 13 | - | |
| $t_{d(off)}$ | Turn-Off Delay Time | | - | 80 | - | |
| t_f | Turn-Off Fall Time | | - | 24 | - | |
| Diode Characteristics | | | | | | |
| V_{DS} | Diode Forward Voltage ^{note3} | $I_S = 2A, V_{GS} = 0V$ | - | - | 1.4 | V |
| t_{rr} | Reverse Recovery Time | $I_{SD} = 4A, V_{GS} = 0V$ | - | 550 | - | ns |
| Q_{rr} | Reverse Recovery Charge | $di_{SD}/dt = 100A/\mu s$ | - | 1.38 | - | nC |

Notes:

- The value of $R_{\theta JC}$ is measured in a still air environment with $T_A = 25^\circ\text{C}$ and the maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design.
- The power dissipation P_D is based on $T_{J(MAX)} = 150^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
- Single pulse width limited by junction temperature $T_{J(MAX)} = 150^\circ\text{C}$.
- The $R_{\theta JA}$ is the sum of the thermal impedance from junction to case $R_{\theta JC}$ and case to ambient.
- The maximum current rating is package limited.
- The EAS data shows Max. rating. The test condition is $V_{DS} = 50V, V_{GS} = 10V, L = 10mH$

Typical Performance Characteristics

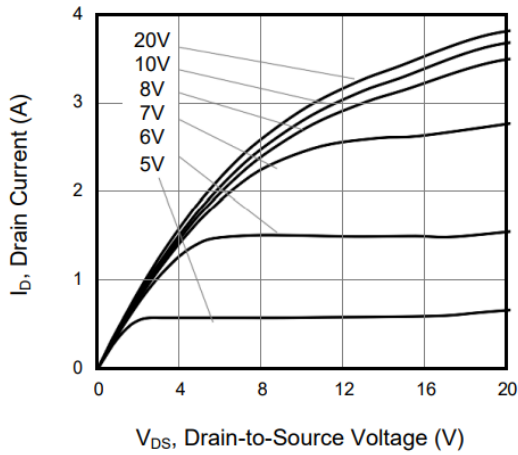


Figure 1. Output Characteristics

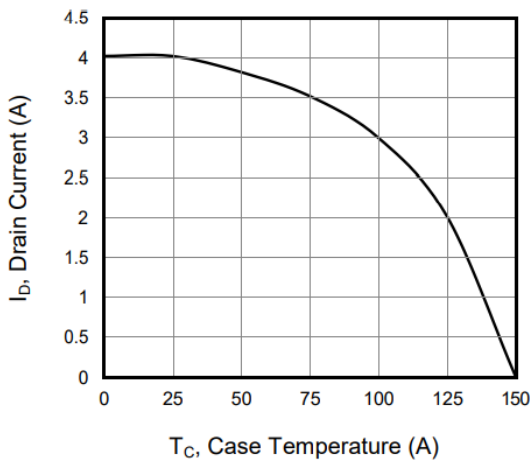


Figure 3. Drain Current vs. Temperature

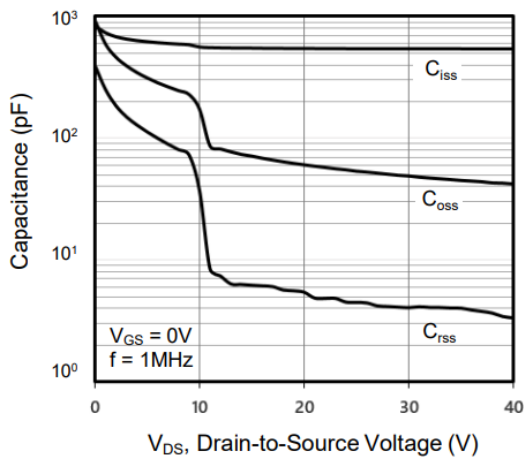


Figure 5. Capacitance Characteristics

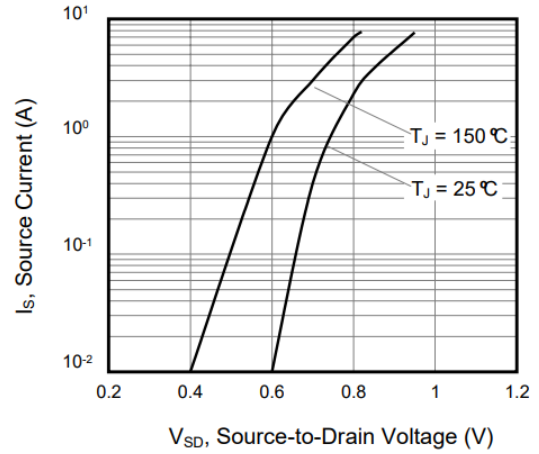


Figure 2. Body Diode Forward Voltage vs Source Current and Temperature

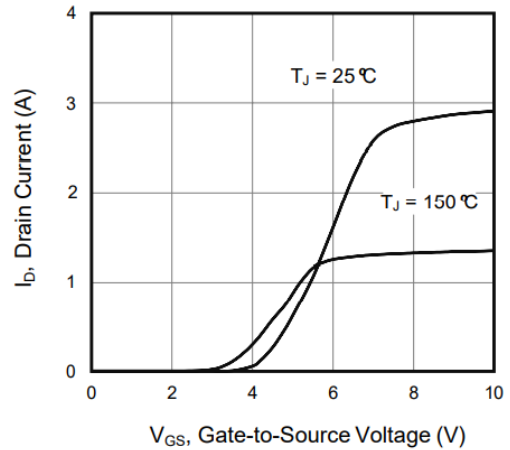


Figure 4. Transfer Characteristics

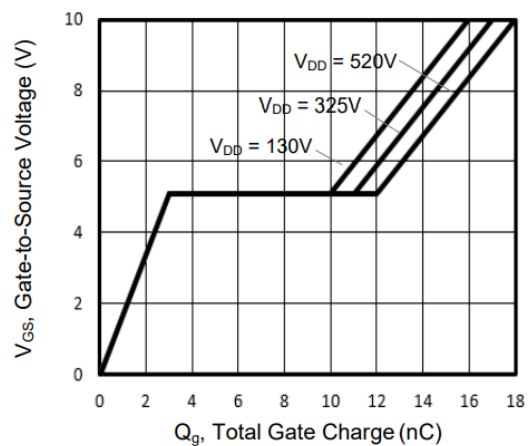


Figure 6. Gate Charge Characteristics

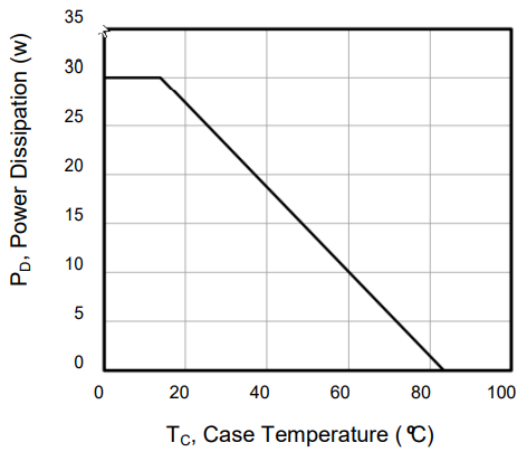


Figure 7. Power Dissipation vs. Temperature

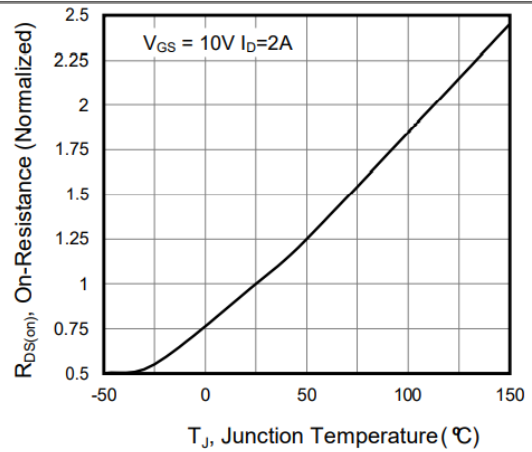


Figure 8. On-Resistance vs. Temperature

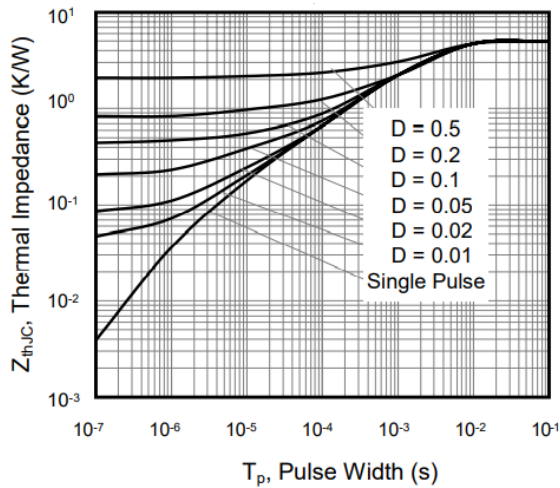
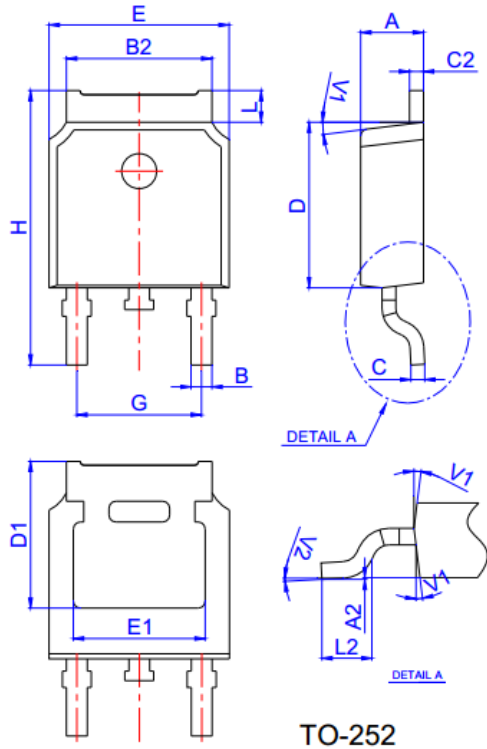


Figure 9. Maximum Effective Transient Thermal Impedance, Junction-to-Case

TO-252 Package Mechanical Data

Package Mechanical Data



| Ref. | Dimensions | | | | | |
|------|-------------|------|-------|----------|------|-------|
| | Millimeters | | | Inches | | |
| | Min. | Typ. | Max. | Min. | Typ. | Max. |
| A | 2.10 | | 2.50 | 0.083 | | 0.098 |
| A2 | 0 | | 0.10 | 0 | | 0.004 |
| B | 0.66 | | 0.86 | 0.026 | | 0.034 |
| B2 | 5.18 | | 5.48 | 0.202 | | 0.216 |
| C | 0.40 | | 0.60 | 0.016 | | 0.024 |
| C2 | 0.44 | | 0.58 | 0.017 | | 0.023 |
| D | 5.90 | | 6.30 | 0.232 | | 0.248 |
| D1 | 5.30REF | | | 0.209REF | | |
| E | 6.40 | | 6.80 | 0.252 | | 0.268 |
| E1 | 4.63 | | | 0.182 | | |
| G | 4.47 | | 4.67 | 0.176 | | 0.184 |
| H | 9.50 | | 10.70 | 0.374 | | 0.421 |
| L | 1.09 | | 1.21 | 0.043 | | 0.048 |
| L2 | 1.35 | | 1.65 | 0.053 | | 0.065 |
| V1 | | 7° | | | 7° | |
| V2 | 0° | | 6° | 0° | | 6° |

WFD5N65LFS Product Description

Silicon N-Channel MOSFET



NOTE:

1. We strongly recommend customers check carefully on the trademark when buying our product, if there is any question, please don't be hesitate to contact us.
2. Please do not exceed the absolute maximum ratings of the device when circuit designing.
3. Winsemi Microelectronics Co., Ltd reserved the right to make changes in this specification sheet and is subject to change without prior notice.

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